MCP1727

1.5A, Low Voltage, Low Quiescent Current LDO Regulator Product Brief

Features

- · 1.5A Output Current Capability
- Input Operating Voltage Range: 2.3V to 6.0V
- Adjustable Output Voltage Range: 0.8V to 5.0V
- · Standard Fixed Output Voltages:
 - 0.8V, 1.2V, 1.8V, 2.5V, 3.0V, 3.3V, 5.0V
- Other Fixed Output Voltage Options Available Upon Request
- · Low Dropout Voltage: 330 mV Typical at 1.5A
- Typical Output Voltage Tolerance: 0.4%
- Stable with 1.0 μF Ceramic Output Capacitor
- · Fast response to Load Transients
- Low Supply Current: 140 μA (typ)
- Low Shutdown Supply Current: 0.1 μA (typ)
- · Adjustable Delay on Power Good Output
- Short Circuit Current Limiting and Overtemperature Protection
- · 3x3 DFN-8 and SOIC-8 Package Options

Applications

- · High-Speed Driver Chipset Power
- · Networking Backplane Cards
- · Notebook Computers
- Network Interface Cards
- · Palmtop Computers
- · 2.5V to 1.XV Regulators

Description

The MCP1727 is a 1.5A Low Dropout (LDO) linear regulator that provides high current and low output voltages in a very small package. The MCP1727 comes in a fixed (or adjustable) output voltage version, with an output voltage range of 0.8V to 5.0V. The 1.5A output current capability, combined with the low output voltage capability, make the MCP1727 a good choice for new sub-1.8V output voltage LDO applications that have high current demands.

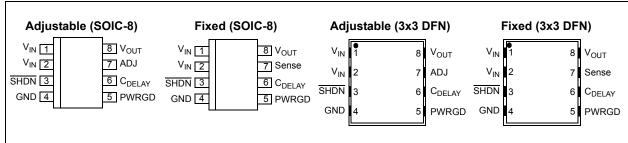
The MCP1727 is stable using ceramic output capacitors that inherently provide lower output noise and reduce the size and cost of the entire regulator solution. Only 1 μ F of output capacitance is needed to stabilize the LDO.

Using CMOS construction, the quiescent current consumed by the MCP1727 is typically less than 140 μ A over the entire input voltage range, making it attractive for portable computing applications that demand high output current. When shut down, the quiescent current is reduced to less than 0.1 μ A.

The scaled-down output voltage is internally monitored and a power good (PWRGD) output is provided when the output is within 92% of regulation (typical). An external capacitor can be used on the C_{DELAY} pin to adjust the delay from 1 ms to 300 ms.

The overtemperature and short circuit current-limiting provide additional protection for the LDO during system fault conditions.

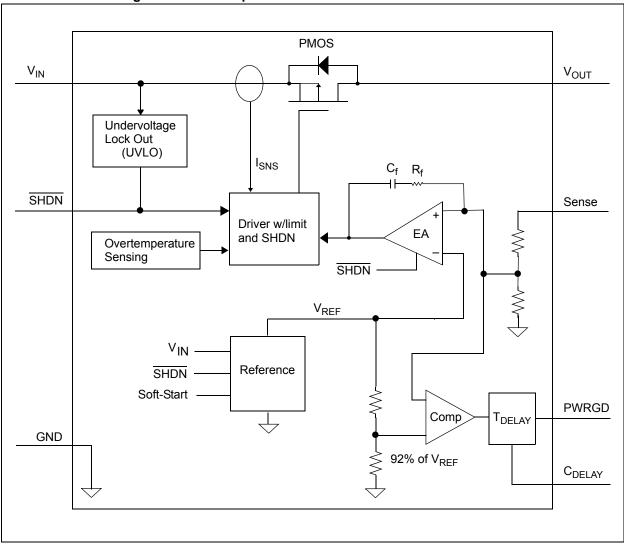
Package Types



Typical Application MCP1727 Fixed Output Voltage $V_{IN} = 2.3V \text{ to } 2.8V$ V_{OUT} = 1.8V @ 1A V_{OUT} V_{IN} 2 V_{IN} Sense C₁ 4.7 μF C₂ 1 μF SHDN C_{DELAY} $\begin{array}{c} {\sf R_1} \\ {\sf 100} \ {\sf k}\Omega \end{array}$ GND PWRGD 5 C₃ 1000 pF On Off **PWRGD** MCP1727 Adjustable Output Voltage V_{OUT} = 1.2V @ 1A 8 V_{IN} V_{OUT} $\begin{array}{c} R_1 \\ 40 \ k\Omega \end{array}$ 2 V_{IN} ADJ SHDN C_{DELAY} 3 $R_3 \lesssim 100 \text{ k}\Omega$ GND PWRGD 5 On C₃ 1000 pF Off **PWRGD**

Functional Block Diagram - Adjustable Output **PMOS** V_{IN} V_{OUT} Undervoltage Lock Out (UVLO) I_{SNS} $C_f \ R_f$ SHDN ADJ Driver w/limit EΑ and SHDN Overtemperature Sensing SHDN V_{REF} V_{IN} -Reference SHDN -Soft-Start -**PWRGD** Comp $\mathsf{T}_{\mathsf{DELAY}}$ GND 92% of V_{REF} $\mathsf{C}_{\mathsf{DELAY}}$

Functional Block Diagram - Fixed Output



1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

 † Notice: Stresses above those listed under "Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

AC-DC CHARACTERISTICS

Electrical Specifications: Unless otherwise noted, $V_{IN} = V_R$ (**Note 2**) + 0.6V, $V_R = 1.8V$ for Adjustable Output, $I_{OUT} = 1$ mA, $C_{IN} = C_{OUT} = 4.7$ µF (X7R Ceramic), $T_A = +25$ °C. **Boldface** type applies for junction temperatures, $T_{.J}$ (**Note 7**) of **-40**°C **to +125**°C

Parameters	Sym	Min	Тур	Max	Units	Conditions	
Input Operating Voltage	V _{IN}	2.3		6.0	V	Note 1	
Input Quiescent Current	Ι _q		140	220	μΑ	$I_L = 0 \text{ mA}, V_{IN} = \text{Note 1}, V_{OUT} = 0.8V \text{ to } 5.0V$	
Input Quiescent Current for SHDN Mode	I _{SHDN}	_	0.1	3	μA	SHDN = GND	
Maximum Output Current	I _{OUT}	1.5	_	_	А	V _{IN} = 2.3V to 6.0V V _R = 0.8V to 5.0V, Note 1	
Line Regulation	ΔV _{OUT} / (V _{OUT} x ΔV _{IN})		0.05	0.15	%/V	(Note 1) \leq V _{IN} \leq 6V	
Load Regulation	$\Delta V_{OUT}/V_{OUT}$	-1.0	±0.5	1.0	%	I _{OUT} = 1 mA to 1.5A, V _{IN} = Note 1 , (Note 4)	
Output Short Circuit Current	I _{OUT_SC}	-	2.2	_	А	V_{IN} = Note 1 , R _{LOAD} < 0.1Ω, Peak Current	
Adjust Pin Characteristics (Adjustable Output Only)							
Adjust Pin Reference Voltage	V_{ADJ}	0.402	0.410	0.418	V	$V_{IN} = 2.3V$ to $V_{IN} = 6.0V$, $I_{OUT} = 1$ mA	
Adjust Pin Leakage Current	I_{ADJ}	-10	±0.01	+10	nA	V _{IN} = 6.0V, V _{ADJ} = 0V to 6V	
Adjust Temperature Coefficient	TCV _{OUT}	_	40	_	ppm/°C	Note 3	
Fixed-Output Characteristics (Fixed Output Only)							

- Note 1: The minimum V_{IN} must meet two conditions: $V_{IN} \ge 2.3 \text{V}$ and $V_{IN} \ge (V_R + 2.5\%) + V_{DROPOUT(MAX)}$.
 - 2: V_R is the nominal regulator output voltage for the fixed cases. V_R = 1.2V, 1.8V, etc. V_R is the desired set point output voltage for the adjustable cases. V_R = $V_{ADJ} \cdot ((R_1/R_2)+1)$. Figure 4-1.
 - 3: TCV_{OUT} = (V_{OUT-HIGH} V_{OUT-LOW}) *10⁶ / (V_R * ΔTemperature). V_{OUT-HIGH} is the highest voltage measured over the temperature range. V_{OUT-LOW} is the lowest voltage measured over the temperature range.
 - **4:** Load regulation is measured at a constant junction temperature using low duty-cycle pulse testing. Load regulation is tested over a load range from 1 mA to the maximum specified output current.
 - 5: Dropout voltage is defined as the input-to-output voltage differential at which the output voltage drops 2% below its nominal value that was measured with an input voltage of V_{IN} = V_R + V_{DROPOUT(MAX)}.
 - 6: The maximum allowable power dissipation is a function of ambient temperature, the maximum allowable junction temperature and the thermal resistance from junction to air. (i.e., T_A, T_J, θ_{JA}). Exceeding the maximum allowable power dissipation will cause the device operating junction temperature to exceed the maximum +150°C rating. Sustained junction temperatures above 150°C can impact device reliability.
 - 7: The junction temperature is approximated by soaking the device under test at an ambient temperature equal to the desired junction temperature. The test time is small enough such that the rise in the junction temperature over the ambient temperature is not significant.

AC-DC CHARACTERISTICS (CONTINUED)

Electrical Specifications: Unless otherwise noted, $V_{IN} = V_R$ (**Note 2**) + 0.6V, $V_R = 1.8V$ for Adjustable Output, $I_{OUT} = 1$ mA, $C_{IN} = C_{OUT} = 4.7 \ \mu F$ (X7R Ceramic), $T_A = +25^{\circ}C$.

Parameters	Sym	Min	Тур	Max	Units	Conditions
Voltage Regulation	V _{OUT}	V _R - 2.5%	V _R ±0.5%	V _R + 2.5%	V	Note 2
Dropout Characteristics						
Dropout Voltage	V_{IN} - V_{OUT}	_	330	525	mV	Note 5, I _{OUT} = 1.5A, V _{IN(MIN)} = 2.3V
Power Good Characteristics						
PWRGD Input Voltage Operating	V _{PWRGD_VIN}	1.0	_	6.0	V	T _A = +25°C
Range		1.2	_	6.0		$T_A = -40^{\circ}C \text{ to } +125^{\circ}C$
						For V _{IN} < 2.3V, I _{SINK} = 100 μA
PWRGD Threshold Voltage (Referenced to V _{OUT})	V _{PWRGD_TH}	89	92	95	%V _{OUT}	Falling Edge
PWRGD Threshold Hysteresis	V _{PWRGD_HYS}	1.0	2.0	3.0	%V _{OUT}	
PWRGD Output Voltage Low	V_{PWRGD_L}	_	0.2	0.4	V	I _{PWRGD SINK} = 1.2 mA, V _{FB} = 0V, C _{DELAY} = GND
PWRGD Leakage	P _{WRGD_LK}		1		nA	$V_{PWRGD} = V_{IN} = 6.0V$
PWRGD Time Delay	T _{PG}					Rising Edge R_{PULLUP} = 10 k Ω
		_	200	_	μs	C _{DELAY} = OPEN
		10	30	55	ms	C _{DELAY} = 0.01 μF
		_	300	_	ms	C _{DELAY} = 0.1 μF
Detect Threshold to PWRGD Active Time Delay	T _{VDET-PWRGD}	_	200	_	μs	V_{ADJ} or V_{SENSE} = V_{PWRGD_TH} + 20 mV to V_{PWRGD_TH} - 20 mV
Shutdown Input						
Logic High Input	V _{SHDN-HIGH}	45			%V _{IN}	V _{IN} = 2.3V to 6.0V
Logic Low Input	V _{SHDN-LOW}			15	%V _{IN}	V _{IN} = 2.3V to 6.0V
SHDN Input Leakage Current	SHDN _{ILK}	-0.1	±0.001	+0.1	μΑ	$\frac{V_{\text{IN}} = 6V, \overline{\text{SHDN}} = V_{\text{IN}},}{\overline{\text{SHDN}} = \overline{\text{GND}}}$
AC Performance						
Output Delay From SHDN	T _{OR}		100		μs	SHDN = GND to V _{IN}

- Note 1: The minimum V_{IN} must meet two conditions: $V_{IN} \ge 2.3 \text{V}$ and $V_{IN} \ge (V_R + 2.5\%) + V_{DROPOUT(MAX)}$.
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 - 3: $TCV_{OUT} = (V_{OUT-HIGH} V_{OUT-LOW}) *10^6 / (V_R * \Delta Temperature)$. $V_{OUT-HIGH}$ is the highest voltage measured over the temperature range. $V_{OUT-LOW}$ is the lowest voltage measured over the temperature range.
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AC-DC CHARACTERISTICS (CONTINUED)

Electrical Specifications: Unless otherwise noted, $V_{IN} = V_{R}$ (**Note 2**) + 0.6V, $V_{R} = 1.8V$ for Adjustable Output, $I_{OUT} = 1$ mA, $C_{IN} = C_{OUT} = 4.7$ µF (X7R Ceramic), $T_{A} = +25$ °C.

Boldface type applies for junction temperatures, T_J (Note 7) of -40°C to +125°C

Parameters	Sym	Min	Тур	Max	Units	Conditions
Output Noise	e _N	1	2.0	1	μV/√Hz	I_{OUT} = 500 mA, f = 1 kHz, C_{OUT} = 10 μ F (X7R Ceramic), V_{OUT} = 2.5V
Power Supply Ripple Rejection Ratio	PSRR	_	60	_	dB	$\begin{split} f &= 100 \text{ Hz, } C_{OUT} = 10 \mu\text{F,} \\ I_{OUT} &= 100 \text{ mA,} \\ V_{INAC} &= 30 \text{ mV pk-pk,} \\ C_{IN} &= 0 \mu\text{F} \end{split}$
Thermal Shutdown Temperature	T _{SD}	_	150	_	°C	I _{OUT} = 100 μA, V _{OUT} = 1.8V, V _{IN} = 2.8V
Thermal Shutdown Hysteresis	ΔT_{SD}	_	10	_	°C	I _{OUT} = 100 μA, V _{OUT} = 1.8V, V _{IN} = 2.8V

- Note 1: The minimum V_{IN} must meet two conditions: $V_{IN} \ge 2.3 \text{V}$ and $V_{IN} \ge (V_R + 2.5\%) + V_{DROPOUT(MAX)}$.
 - 2: V_R is the nominal regulator output voltage for the fixed cases. V_R = 1.2V, 1.8V, etc. V_R is the desired set point output voltage for the adjustable cases. V_R = V_{ADJ} ((R_1/R_2)+1). Figure 4-1.
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TEMPERATURE SPECIFICATIONS

Electrical Specifications: Unless otherwise indicated, all limits apply for V _{IN} = 2.3V to 6.0V.						
Parameters	Sym	Min	Тур	Max	Units	Conditions
Temperature Ranges						
Operating Junction Temperature Range	T _J	-40	_	+125	°C	Steady State
Maximum Junction Temperature	T_J	_	_	+150	°C	Transient
Storage Temperature Range	T _A	-65	_	+150	°C	
Thermal Package Resistances	-					
Thermal Resistance, 8LD 3x3 DFN	θ_{JA}	_	41	_	°C/W	4-Layer JC51-7 Standard Board with vias
Thermal Resistance, 8LD SOIC	θ_{JA}	_	150	_	°C/W	4-Layer JC51-7 Standard Board

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